

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT6883917

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| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                         |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                             |
| <b>CONVEYING PARTY DATA</b>   |  |
| <b>Name</b>   | <b>Execution Date</b>                  |
| MD ZAKIR ULLAH  | 04/14/2021                             |
| XIAOSONG ZHANG  | 04/07/2021                             |
| ADAM L. OLSON   | 04/02/2021                             |
| MOHAMMAD MOYDUL ISLAM   | 04/14/2021                             |
| TIEN MINH QUAN TRAN   | 04/01/2021                             |
| CHAO ZHU  | 08/24/2021                             |
| ZHIGANG YANG  | 05/14/2021                             |
| MERRI L. CARLSON  | 03/31/2021                             |
| HUI CHIN CHONG  | 04/10/2021                             |
| KOK SIAK TANG   | 04/05/2021                             |
| <b>RECEIVING PARTY DATA</b>   |  |
| <b>Name:</b>  | MICRON TECHNOLOGY, INC.                |
| <b>Street Address:</b>  | 8000 SOUTH FEDERAL WAY, MAILSTOP 1-507 |
| <b>City:</b>  | BOISE                                  |
| <b>State/Country:</b>   | IDAHO                                  |
| <b>Postal Code:</b>   | 83707-0006                             |
| <b>PROPERTY NUMBERS Total: 1</b>  |  |
| <b>Property Type</b>  | <b>Number</b>                          |
| Application Number:   | 17016002                               |
| <b>CORRESPONDENCE DATA</b>  |  |
| <b>Fax Number:</b>  | (801)531-9168                          |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |  |
| <b>Phone:</b>   | 8015321922                             |
| <b>Email:</b>   | mebriggs@traskbritt.com                |
| <b>Correspondent Name:</b>  | TRASKBRITT                             |
| <b>Address Line 1:</b>  | 230 SOUTH 500 EAST, SUITE 300          |
| <b>Address Line 4:</b>  | SALT LAKE CITY, UTAH 84102             |
| <b>ATTORNEY DOCKET NUMBER:</b>  | 2269-15531(2019-2425.00)               |

|                           |                              |
|---------------------------|------------------------------|
| <b>NAME OF SUBMITTER:</b> | ELIZABETH HERBST SCHIERMAN   |
| <b>SIGNATURE:</b>         | /Elizabeth Herbst Schierman/ |
| <b>DATE SIGNED:</b>       | 08/25/2021                   |

**Total Attachments: 30**

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**ASSIGNMENT**

**FOR GOOD AND VALUABLE CONSIDERATION**, the receipt, sufficiency and adequacy of which are hereby acknowledged, each undersigned ASSIGNOR does hereby:

**SELL, ASSIGN AND TRANSFER to MICRON TECHNOLOGY, INC.** ("ASSIGNEE"), a corporation of the State of Delaware, having a place of business at 8000 South Federal Way, Mailstop 1-507, Boise, ID 83707-0006, the entire right, title and interest for the United States and all foreign countries in and to any and all improvements that are disclosed in the **Application for United States Letters Patent Serial No. 17/016,002** filed on **September 9, 2020**, and titled **MICROELECTRONIC DEVICES WITH TIERED DECKS OF DIFFERING PILLAR DENSITY AND RELATED METHODS AND SYSTEMS**, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof that have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents that have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

**AUTHORIZE** the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;

**AUTHORIZE AND REQUEST** the issuing authority to issue any and all United States and foreign patents granted on such improvements to and in the name of the ASSIGNEE;

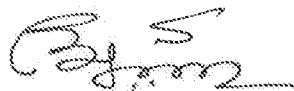
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**COVENANT**, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this Assignment, to execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications relating to any and all such improvements; to execute all rightful oaths, declarations, assignments, powers of attorney and other papers; to communicate to the ASSIGNEE all facts and provide to the ASSIGNEE all documents and things known and accessible to the undersigned relating to such improvements and the history thereof, and testify as to the same in any interference, litigation or other proceeding relating thereto; and generally to do everything possible that the ASSIGNEE shall

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ASSIGNOR(S):

  
Date: 04/14/2021  
Md Zakir Ullah  
Mailing address: The Quintet, Block 44, #14-17, Choa Chu Kang Street 64, Singapore 689105

Date: \_\_\_\_\_  
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Mailing address: 6563 E Bend Ridge Street, Boise, ID 83716

Date: \_\_\_\_\_  
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Mailing address: 5757 E Hootowl Drive, Boise, ID 83716

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Date: \_\_\_\_\_

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Date: \_\_\_\_\_

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David A. Kewley

Mailing address: 4683 South Silverpine Way, Boise, ID 83709

Date: \_\_\_\_\_

Kok Siak Tang

Mailing address: Block 108C McNair Road, #03-212, Singapore 324108

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
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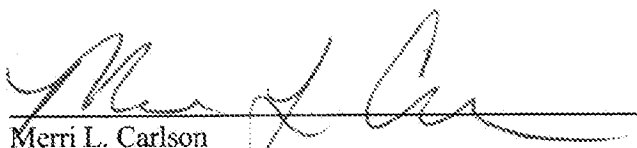
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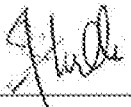
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